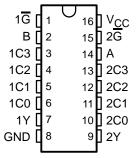


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- AC Types Feature 1.5-V to 5.5-V Operation and Balanced Noise Immunity at 30% of the Supply
- Speed of Bipolar F, AS, and S, With Significantly Reduced Power Consumption
- Balanced Propagation Delays
- ±24-mA Output Drive Current
 - Fanout to 15 F Devices
- SCR-Latchup-Resistant CMOS Process and Circuit Design
- Exceeds 2-kV ESD Protection Per MIL-STD-883, Method 3015

CD54AC153...F PACKAGE CD74AC153...E OR M PACKAGE (TOP VIEW)



description/ordering information

Each of these data selectors/multiplexers contains inverters and drivers to supply full binary decoding data selection to the AND-OR gates. Separate strobe (\overline{G}) inputs are provided for each of the two 4-line sections.

ORDERING INFORMATION

TA	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – E	Tube	CD74AC153E	CD74AC153E
–55°C to 125°C	SOIC – M	Tube	CD74AC153M	AC153M
-55 C to 125 C	SOIC - IVI	Tape and reel	CD74AC153M96	AC 155IVI
	CDIP – F	Tube	CD54AC153F3A	CD54AC153F3A

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

	INPUTS										
SELE	ЕСТ‡		DA	·ΤΑ		G	OUTPUT Y				
В	Α	C0	C1	C2	C3	Ğ					
Х	Χ	Х	Χ	X	Χ	Н	L				
L	L	L	X	X	X	L	L				
L	L	Н	Χ	X	Χ	L	Н				
L	Н	Х	L	X	Χ	L	L				
L	Н	Х	Н	X	Χ	L	Н				
н	L	Х	Χ	L	Χ	L	L				
Н	L	Х	Χ	Н	Χ	L	Н				
Н	Н	Х	Χ	Χ	L	L	L				
Н	Н	Х	Χ	Χ	Н	L	Н				

[‡] Select inputs A and B are common to both sections.

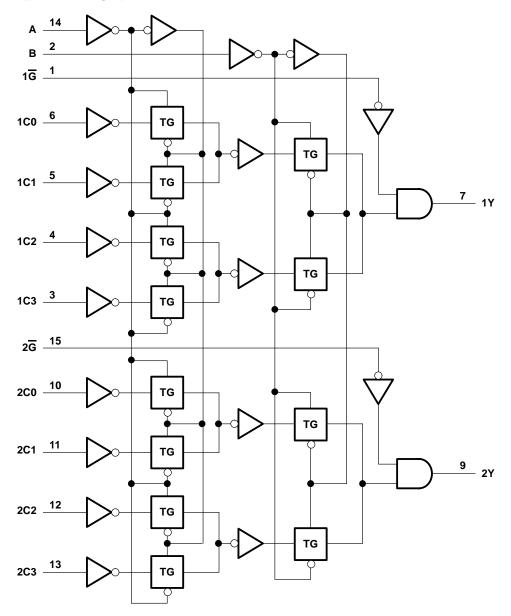


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logic diagram (positive logic)



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absolute maximum ratings over operating free-air temperature range†

Supply voltage range, V _{CC}	
Input clamp current, $I_{ K }(V_1 < 0 \text{ or } V_1 > V_{CC})$ (see Note 1)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see Note 1)	±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Package thermal impedance, θ_{JA} (see Note 2): E package	67°C/W
M package	
Storage temperature range, T _{stg}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

			T _A = 25°C		–55°C to 125°C		–40°C to 85°C		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
Vсс	Supply voltage		1.5	5.5	1.5	5.5	1.5	5.5	V
		V _{CC} = 1.5 V	1.2		1.2		1.2		
ViH	High-level input voltage	V _{CC} = 3 V	2.1		2.1		2.1		V
		V _{CC} = 5.5 V	3.85		3.85		3.85		
		V _{CC} = 1.5 V		0.3		0.3		0.3	
VIL	Low-level input voltage	VCC = 3 V		0.9		0.9		0.9	V
		V _{CC} = 5.5 V		1.65		1.65		1.65	
٧ _I	Input voltage		0	VCC	0	VCC	0	VCC	V
٧o	Output voltage		0	VCC	0	VCC	0	VCC	V
lон	High-level output current	V _{CC} = 4.5 V to 5.5 V		-24		-24		-24	mA
loL	Low-level output current	V _{CC} = 4.5 V to 5.5 V		24		24		24	mA
Δt/Δν	langet transition rise or fall rate	V _{CC} = 1.5 V to 3 V		50		50		50	ns/V
ΔυΔν	Input transition rise or fall rate	$V_{CC} = 3.6 \text{ V to } 5.5 \text{ V}$		20		20		20	115/V

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONI	Vcc	T _A = 2	25°C	–55°C to 125°C		–40°C to 85°C		UNIT		
			MIN	MAX	MIN	MAX	MIN	MAX			
			1.5 V	1.4		1.4		1.4			
		$I_{OH} = -50 \mu A$	3 V	2.9		2.9		2.9			
			4.5 V	4.4		4.4		4.4			
Voн	VI = VIH or VIL	I _{OH} = -4 mA	3 V	2.58		2.4		2.48		V	
		$I_{OH} = -24 \text{ mA}$	4.5 V	3.94		3.7		3.8			
		$I_{OH} = -50 \text{ mA}^{\dagger}$	5.5 V		3.85						
		$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V					3.85			
			1.5 V		0.1		0.1		0.1		
		I _{OL} = 50 μA	I _{OL} = 50 μA	3 V		0.1		0.1		0.1	
			4.5 V		0.1		0.1		0.1		
VOL	VI = VIH or VIL	I _{OL} = 12 mA	3 V		0.36		0.5		0.44	V	
		I _{OL} = 24 mA	4.5 V		0.36		0.5		0.44		
		$I_{OL} = 50 \text{ mA}^{\dagger}$	5.5 V				1.65				
		I _{OL} = 75 mA [†]	5.5 V						1.65		
lį	V _I = V _{CC} or GND		5.5 V		±0.1		±1		±1	μΑ	
Icc	$V_I = V_{CC}$ or GND,	IO = 0	5.5 V		8		160		80	μΑ	
Ci					10		10		10	pF	

[†] Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 1.5 V, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55°C to 125°C	–40°C to 85°C	UNIT
	(HAPOT)	(001F01)	MIN MAX	MIN MAX	
^t PLH	A or B	v	250	227	ns
^t PHL	AUB	ı	250	227	115
^t PLH	Any C	v	166	151	ns
^t PHL	Ally C	'	166	151	115
^t PLH	ĪG	~	148	134	
t _{PHL}	9	r	148	134	ns

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switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55°(125		–40°0 85°	UNIT	
	(1141 01)	(6611 61)	MIN	MAX	MIN	MAX	
^t PLH	A or B	V	7	28	7.2	25.5	ns
^t PHL	A 01 B	1	7	28	7.2	25.5	115
t _{PLH}	Any C	~	4.7	18.6	4.8	16.9	ne
^t PHL	Ally C	1	4.7	18.6	4.8	16.9	ns
^t PLH	G		4.1	16.5	4.3	15	ne
^t PHL	G	ĭ	4.1	16.5	4.3	15	ns

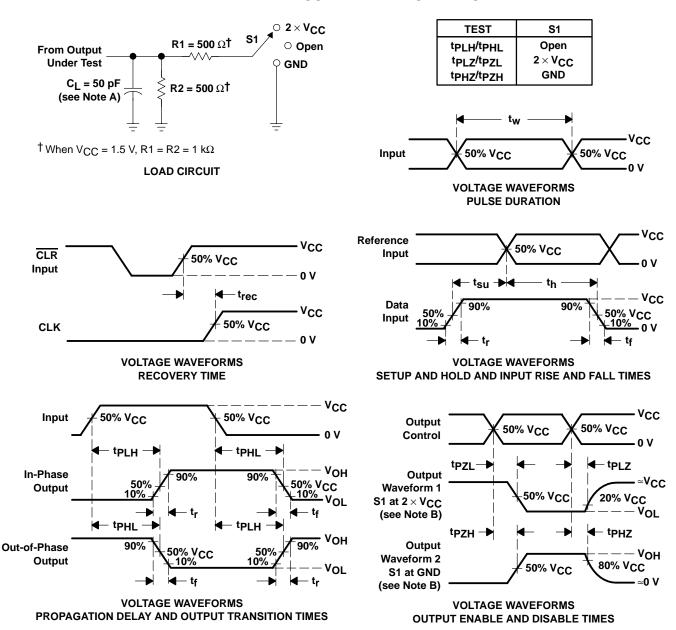
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO (OUTPUT)	–55°(125		–40°(85°	UNIT	
	(INPUT) (OUTPUT)		MIN	MAX	MIN	MAX	
^t PLH	A or B	~	5	20	5.2	18.2	ne
^t PHL	A 01 B	1	5	20	5.2	18.2	ns
t _{PLH}	Any C	~	3.3	13.3	3.4	12.1	ne
^t PHL	Ally C	1	3.3	13.3	3.4	12.1	ns
^t PLH	G	·	3	11.8	3.1	10.7	ne
tPHL	9	r	3	11.8	3.1	10.7	ns

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TYP	UNIT
C _{pd}	Power dissipation capacitance	93	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \ \Omega$, $t_f = 3 \ ns$, $t_f = 3 \ ns$. Phase relationships between waveforms are arbitrary.
- D. For clock inputs, f_{max} is measured with the input duty cycle at 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. tpLH and tpHL are the same as tpd.
- G. tpzL and tpzH are the same as ten.
- H. tpLZ and tpHZ are the same as tdis.
- I. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms







i.com 26-Sep-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
CD54AC153F3A	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
CD74AC153E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD74AC153EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD74AC153M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	k CU NIPDAU	Level-1-260C-UNLIM
CD74AC153M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	k CU NIPDAU	Level-1-260C-UNLIM
CD74AC153M96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	k CU NIPDAU	Level-1-260C-UNLIM
CD74AC153ME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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14 LEADS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AC.



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